Annual Member Meeting
26th – 27th February 2014
San Jose, CA
Hosted by Flextronics

Wednesday 26th February – Open Day for Members and Guests

8:00 Registration, coffee and socializing

8:30 Opening of the meeting – Marshall Andrews, HDP User Group
- Self-Introduction of Participants - All
- Welcome and introduction to Flextronics– Murad Kurwa VP, Advanced Engineering Group
- Introduction of new members
- Awards

Projects Review/Status Update– Chair: Jack Fisher, HDP User Group

9:20
- Through Silicon Vias (TSV) – Dave Love, HDP User Group
- Press Fit Rework Project– Lars Bruno, Ericsson / Jack Fisher, HDP User Group
- Anti-Counterfeit Electronics II- Colm Nolan, IBM / Laurence Schultz

10:30 Break

10:50
- Pb-Free Mini Power Cycles – Igor Perez, Ericsson / Larry Marcanti HDP User Group
- Electro-Chemical Migration on PCBs – Mike Bixenman, Kyzen

11:30 PCB Enabling Technology – Raj Kumar, V.P. of Technology, Viasystems

12:15 Lunch

13:15
- Low Silver SAC Solder Paste – Jennifer Nguyen, Flextronics
- Ultra-Thin HDI Multi-Purpose Test Vehicle – Chris Katzko, TTM Meadville
- Pb-Free PWB Materials Reliability Phase 4 – John Wilson, IBM / Brian Smith, HDP User Group
- Opto- Electronics II –Brice Achkir, Cisco

14:50 Break

15:10
- PWB Back Drilling – P C Wong, PWB Interconnect Solutions / John Davignon, HDP User Group
- BFR/PVC – Free Cables II – James Baker, Loron
- Fine Pitch Optical Components- Laye Fenglei, Huawei / Larry Marcanti, HDP User Group

16:10 **New Project Proposals**
- Future HDI – Joe Smetana/Ivan Straznicky, Alcatel-Lucent/ Curtiss Wright
- Micro-bump solder joints – Dongji Xie, Nvidia
- Other new project proposals
- Round Table Discussion – Chaired by Jack Fisher, HDP User Group

16:45 Feedback from Guests

17:00 Close of meeting

19:00 Dinner

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Thursday 27th September – Members Only Session

8:00 Coffee and socializing

8:30 Opening of the meeting – Marshall Andrews, HDP User Group

8:35 HDP Board of Directors Report – Thilo Sack, Chairman HDP User Group Board

8:50 HDP Updates – Marshall Andrews, HDP User Group

Projects Review/Status Update– Chair: Jack Fisher, HDP User Group

9:15 New Technology Projects
- PCB / Package Warpage – Kirk Van Dreel, Plexus
- Polymer Ball Interconnect – Jim Jones, Oracle / Brian Smith, HDP User Group
- Opto Interconnect Phase 1 –Brice Achkir, Cisco

10:30 Break

10:50 PWB Level Implementation Projects
- High Speed PWB Materials – Karl Sauter, Oracle
- Pad Cratering – Thilo Sack, Celestica
- Lead Free Board Materials Reliability III – John Wilson, IBM / Brian Smith HDP user Group

12:00 Lunch

13:00 PWB Implementation Projects (Cont'd)
- Multiple Lamination PWBs – Ivan Straznicky, Curtiss-Wright
- PWB Environmental Life Cycle Analysis – Erkko Helminen, TTM Meadville , Brian Smith HDP

Pb-Free Assembly Implementation Projects
- SAC Aging II / SAC Future Work – Jim Wilcox, HDP User Group
- Process Sensitive Components – Marie Cole, IBM

15:00 Break

15:15 Pb-Free Assembly Implementation Projects (Cont'd)
- Lead Free Copper Erosion – Keith Howell, Nihon Superior
- Board Mounted Power Supplies – Leif Hutchinson, Juniper
- Thin Copper Stress Test – Shunichi Kikuchi, Fujitsu / Marshall Andrews, HDP User Group

16:30 Any Other Business and Feedback from Attendees

17:00 Close

19:00 Dinner